

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	155830	(semiconductor or die or chip or IC) and (double or dual)	USPAT	2004/03/19 23:38
2	BRS	5905	(semiconductor or die or chip or IC) with (double or dual) and lead	USPAT	2004/03/18 19:30
3	BRS	2915	((semiconductor or die or chip or IC) with (double or dual) and lead) and "257"	USPAT	2004/03/18 19:30
4	BRS	723	((semiconductor or die or chip or IC) with (double or dual) and lead) and (die near pad or paddle)	USPAT	2004/03/18 19:44
5	BRS	353	((semiconductor or die or chip or IC) with (double or dual) and lead) and (electrodes or terminals or contacts or pads) near (top or upper) and (electrodes or terminals or contacts or pads) near (bottom or lower)	USPAT	2004/03/18 20:44
6	BRS	46	((semiconductor or die or chip or IC) with (double or dual) and lead) and (electrodes or terminals or contacts or pads) near (top or upper) and (electrodes or terminals or contacts or pads) near (bottom or lower) ) and (die near pad or paddle)	USPAT	2004/03/18 20:01

	Type	Hits	Search Text	DBs	Time Stamp
7	BRS	307	((semiconductor or die or chip or IC) with (double or dual) and lead) and (electrodes or terminals or contacts or pads) near (top or upper) and (electrodes or terminals or contacts or pads) near (bottom or lower) ) not (((semiconductor or die or chip or IC) with (double or dual) and lead) and (electrodes or terminals or contacts or pads) near (top or upper) and (electrodes or terminals or contacts or pads) near (bottom or lower) ) and (die near pad or paddle))	USPAT	2004/03/18 20:02
8	BRS	404	((semiconductor or die or chip or IC) with (double or dual) and lead) and (electrodes or terminals or contacts or pads) near (both)	USPAT	2004/03/18 21:19
9	BRS	311926	(electrodes or terminals or contacts or pads) with both surfaces near (semiconductor or die or chip or IC)	USPAT	2004/03/18 21:20
10	BRS	81248	( pads) with both surfaces near (semiconductor or die or chip or IC)	USPAT	2004/03/18 21:20
11	BRS	48	( pads) with (both near surfaces) near (semiconductor or die or chip or IC)	USPAT	2004/03/18 21:35
12	BRS	1092	( ((semiconductor or die or chip or IC) near pad or paddle) with electri\$6 with connect\$3 with (semiconductor or die or chip or IC) ) with lead	USPAT	2004/03/18 21:37

	Type	Hits	Search Text	DBs	Time Stamp
13	BRS	734	(( ((semiconductor or die or chip or IC) near pad or paddle) with electri\$6 with connect\$3 with (semiconductor or die or chip or IC) ) with lead) with wir\$3	USPAT	2004/03/19 10:46
14	BRS	734	(( ((semiconductor or die or chip or IC) near pad or paddle) with electri\$6 with connect\$3 with (semiconductor or die or chip or IC) ) with lead) with wir\$3	USPAT	2004/03/19 10:46
15	BRS	2589	(( (semiconductor or die or chip or IC) near pad or paddle) with electri\$6 with connect\$3 with (semiconductor or die or chip or IC) )	USPAT	2004/03/19 11:05
16	BRS	35	(( (semiconductor or die or chip or IC) near pad or paddle) with electri\$6 with connect\$3 with (back or rear) near surface with (semiconductor or die or chip or IC) )	USPAT	2004/03/19 10:48
17	BRS	62	(( (semiconductor or die or chip or IC) near pad or paddle) with electri\$6 with connect\$3 with (back or rear) with (semiconductor or die or chip or IC) )	USPAT	2004/03/19 10:48
18	BRS	544	L and (semiconductor or die or chip or IC) with (top or upper) with pad and (semiconductor or die or chip or IC) with (bottom or rear) with pad	USPAT	2004/03/19 11:07

	Type	Hits	Search Text	DBs	Time Stamp
19	BRS	369	((((semiconductor or die or chip or IC) near pad or paddle) with electri\$6 with connect\$3 with (semiconductor or die or chip or IC) ) ) and (semiconductor or die or chip or IC) with (top or upper) with pad and (semiconductor or die or chip or IC) with (bottom or rear) with pad	USPAT	2004/03/19 11:41
20	BRS	369	(((((semiconductor or die or chip or IC) near pad or paddle) with electri\$6 with connect\$3 with (semiconductor or die or chip or IC) ) ) and (semiconductor or die or chip or IC) with (top or upper) with pad and (semiconductor or die or chip or IC) with (bottom or rear) with pad ) and electr\$6	USPAT	2004/03/19 11:42
21	BRS	175	(((((semiconductor or die or chip or IC) near pad or paddle) with electri\$6 with connect\$3 with (semiconductor or die or chip or IC) ) ) and (semiconductor or die or chip or IC) with (top or upper) with pad and (semiconductor or die or chip or IC) with (bottom or rear) with pad ) and electr\$6 with die near pad	USPAT	2004/03/19 11:42

	Type	Hits	Search Text	DBs	Time Stamp
22	BRS	175	(((((semiconductor or die or chip or IC) near pad or paddle) with electri\$6 with connect\$3 with (semiconductor or die or chip or IC) ) ) and (semiconductor or die or chip or IC) with (top or upper) with pad and (semiconductor or die or chip or IC) with (bottom or rear) with pad ) and (electr\$6 or ground) with die near pad	USPAT	2004/03/19 11:43
23	BRS	2589	((semiconductor or die or chip or IC) near pad or paddle) with electri\$6 with connect\$3 with (semiconductor or die or chip or IC)	USPAT	2004/03/19 19:01
24	BRS	247	((semiconductor or die or chip or IC) near pad or paddle) with electri\$6 with connect\$3 with (semiconductor or die or chip or IC) ) and ((semiconductor or die or chip or IC) near pad or paddle) with ground	USPAT	2004/03/20 00:03
25	BRS	1	"6337521".PN.	USPAT	2004/03/19 19:11
26	BRS	1	"6353265".PN.	USPAT	2004/03/19 19:12
27	BRS	1	"4698663".PN.	USPAT	2004/03/19 20:07
28	BRS	1	"5048179".PN.	USPAT	2004/03/19 20:08
29	BRS	1	"5367193".PN.	USPAT	2004/03/19 20:08
30	BRS	1	"5455457".PN.	USPAT	2004/03/19 20:08

	Type	Hits	Search Text	DBs	Time Stamp
31	BRS	1	"5561323".PN.	USPAT	2004/ 03/19 20:09
32	BRS	1	"5729435".PN.	USPAT	2004/ 03/19 20:09
33	BRS	1	"5744863".PN.	USPAT	2004/ 03/19 20:09
34	BRS	1	"5767446".PN.	USPAT	2004/ 03/19 20:09
35	BRS	1	"5818699".PN.	USPAT	2004/ 03/19 20:09
36	BRS	1	"5835988".PN.	USPAT	2004/ 03/19 20:10
37	BRS	397	((semiconductor or die or chip or IC) near pad or paddle) with connect\$3 with ground	USPAT	2004/ 03/19 20:11
38	BRS	7	"5767570"	USPAT	2004/ 03/19 23:25
39	BRS	1	"5340771".PN.	USPAT	2004/ 03/19 23:26
40	BRS	1	"5534467".PN.	USPAT	2004/ 03/19 23:26
41	BRS	8	"5534467"	USPAT	2004/ 03/19 23:29
42	BRS	25	"5340771"	USPAT	2004/ 03/19 23:29
43	BRS	1165	(semiconductor or die or chip or IC) near (double or dual)	USPAT	2004/ 03/19 23:39
44	BRS	1117	((semiconductor or die or chip or IC) near pad or paddle) with electri\$6 with connect\$3 with lead	USPAT	2004/ 03/20 00:04
45	BRS	724	((semiconductor or die or chip or IC) near pad or paddle) with electri\$6 with connect\$3 with lead with wire	USPAT	2004/ 03/20 00:22

	Type	Hits	Search Text	DBs	Time Stamp
46	BRS	1813	((semiconductor or die or chip or IC) near pad or paddle) with lead with wir\$3) not ((semiconductor or die or chip or IC) near pad or paddle) with electri\$6 with connect\$3 with lead with wire)	USPAT	2004/03/20 01:07
47	BRS	1813	((semiconductor or die or chip or IC) near pad or paddle) with lead with wir\$3) not ((semiconductor or die or chip or IC) near pad or paddle) with electri\$6 with connect\$3 with lead with wire)	USPAT	2004/03/20 01:08
48	BRS	2537	((semiconductor or die or chip or IC) near pad or paddle) with lead with wir\$3	USPAT	2004/03/20 01:09
49	BRS	2540	((semiconductor or die or chip or IC) near pad or paddle) with lead with (wiring or wire or wired)	USPAT	2004/03/20 01:10
50	BRS	75	((semiconductor or die or chip or IC) near pad or paddle) with lead with (wiring or wire or wired) same ground with connect\$3	USPAT	2004/03/20 13:56
51	BRS	384	257/777 and (airgel or air or porous)	USPAT	2004/03/20 15:05
52	BRS	39	257/777 and (airgel or porous)	USPAT	2004/03/20 17:53
53	BRS	62	(257/670 or 257/671 or 257/676) and ((die or chip or IC) near pad or paddle or pallet) with ground with connect\$3	USPAT	2004/03/20 18:01
54	BRS	17	(257/686 or 257/685 or 257/689) and ((die or chip or IC) near pad or paddle or pallet) with ground with connect\$3	USPAT	2004/03/20 18:04

	Type	Hits	Search Text	DBs	Time Stamp
55	BRS	680	(257/713 or 257/777 or 257/778 or 257/787) and ((die or chip or IC) near pad or paddle or pallet) with electr\$6 with connect\$3	USPAT	2004/03/20 18:28
56	BRS	330	(361/760 or 438/108 or 438/109) and ((die or chip or IC) near pad or paddle or pallet) with electr\$6 with connect\$3	USPAT	2004/03/20 18:27
57	BRS	375	(361/760 or 438/108 or 438/109) and ((die or chip or IC) near pad or paddle or pallet) with electr\$6 with connect\$3	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2004/03/20 18:20
58	BRS	45	(361/760 or 438/108 or 438/109) and ((die or chip or IC) near pad or paddle or pallet) with electr\$6 with connect\$3	US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2004/03/20 18:27
59	BRS	119	(257/713 or 257/777 or 257/778 or 257/787) and ((die or chip or IC) near pad or paddle or pallet) with electr\$6 with connect\$3	US-PGPU B; EPO; JPO; DERWENT ; IBM_TDB	2004/03/20 18:28